

Surface Mount General Purpose Silicon Rectifier 表面贴装整流管

Reverse Voltage - 1000 V 电压范围

Forward Current - 1 A 电流

FEATURES 特征

- For surface mounted applications 表面贴装应用
- Low profile package 侧面封装低
- Glass Passivated Chip Junction 玻璃钝化芯片
- Easy to pick and place 容易放置

MECHANICAL DATA 机械数据

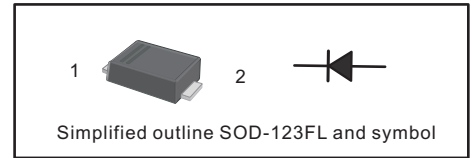
- Case: SOD-123FL
封装：SOD-123FL
- Approx. Weight: 20mg / 0.00085oz
重量：20mg

Maximum Ratings and Electrical characteristics 极值和电子特性

Ratings at 25 °C ambient temperature unless otherwise specified. TA = 25°C 除非另有规定。
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Parameter	Symbols	A8	Units
反向重复峰值电压	V_{RRM}	1200	V
均方根电压	V_{RMS}	700	V
直流阻值电压	V_{DC}	1200	V
正向平均整流电流	$I_{F(AV)}$	1	A
正向浪涌峰值电流	I_{FSM}	50	A
正向电压	V_F	0.91	V
反向峰值漏电流	I_R	5 100	μA
结电容 ⁽¹⁾	C_j	15	pF
热阻（结到环境） ⁽²⁾	$R_{\theta JA}$	35	°C/W
结温，存储温度	T_j, T_{stg}	-55 ~ +150	°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 cm) copper pad areas.

特性曲线

Fig.1 Forward Current Derating Curve
正向降额曲线

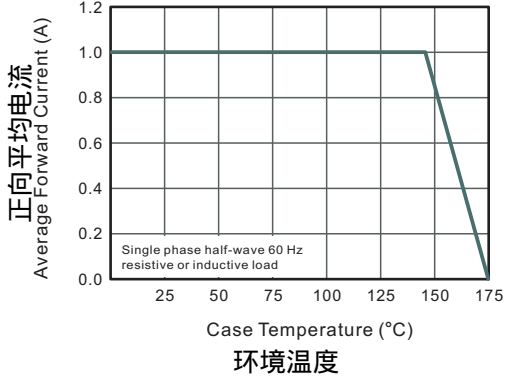


Fig.2 Typical Instaneous Reverse Characteristics 反向特性

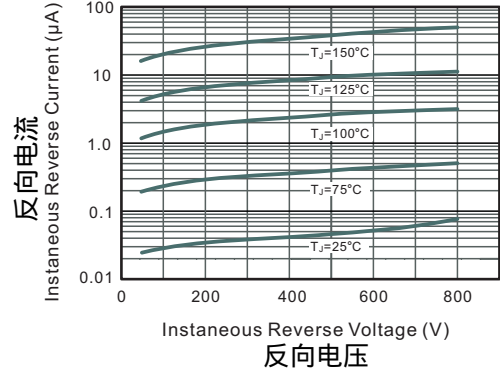


Fig.3 Typical Forward Characteristic

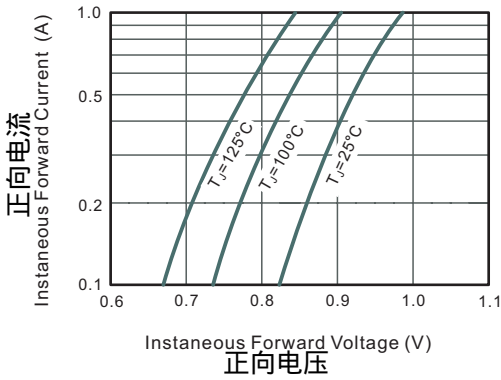


Fig.4 Typical Junction Capacitance

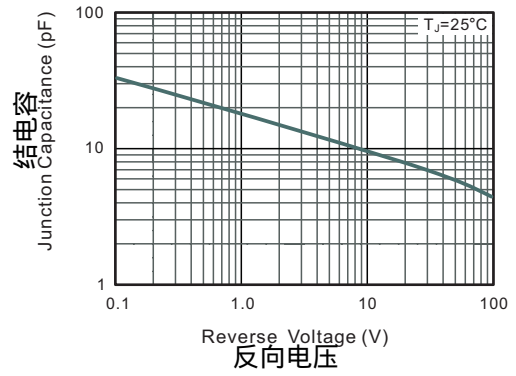
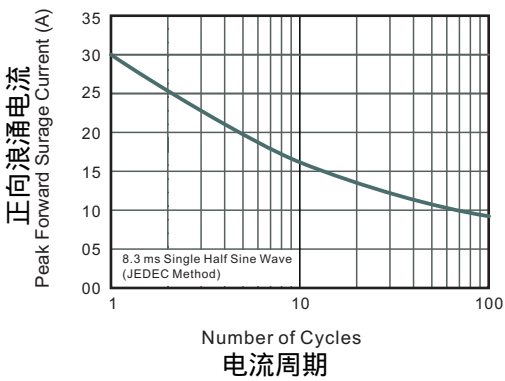


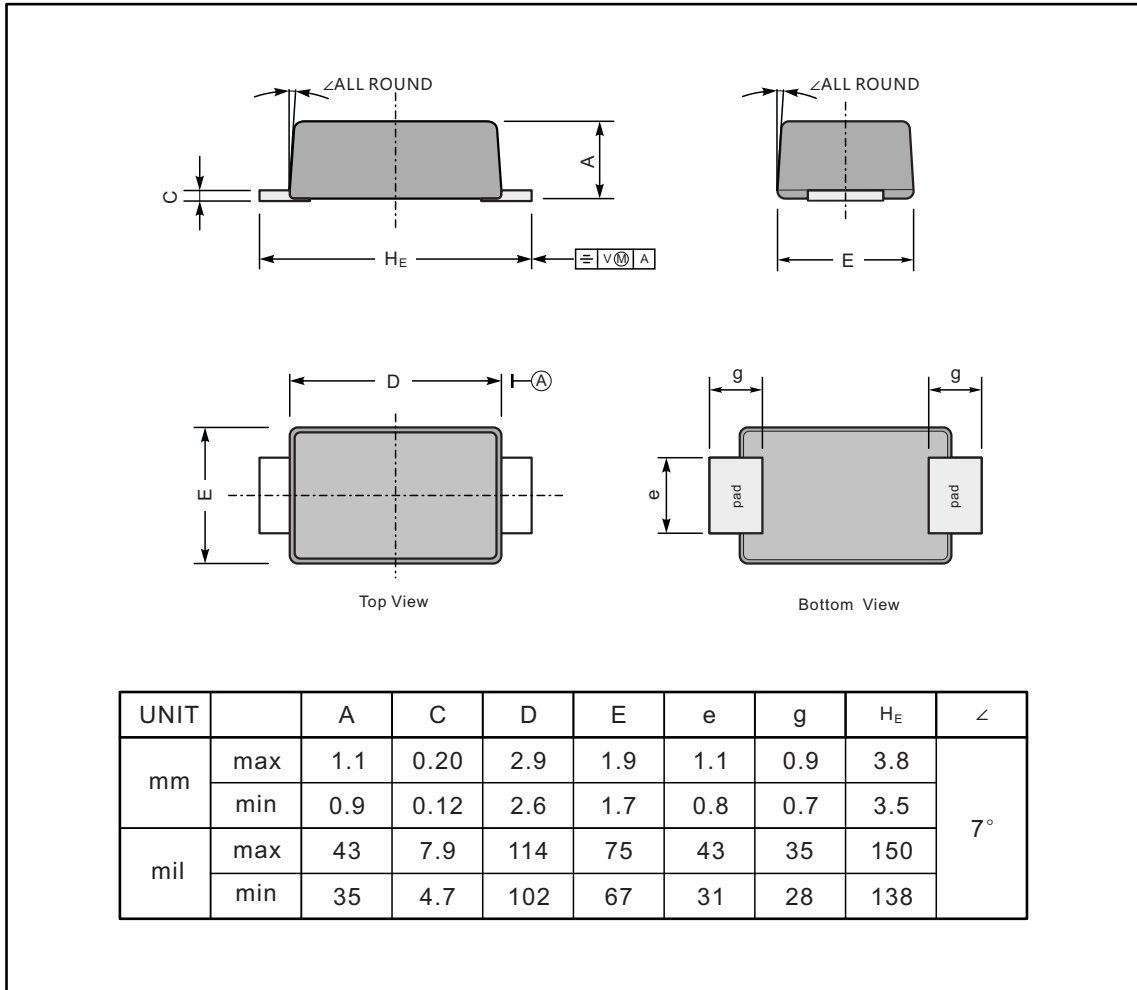
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



PACKAGE OUTLINE 封装尺寸

Plastic surface mounted package; 2 leads

SOD-123FL



The recommended mounting pad size 贴装板尺寸

